

### Features

- 1 A maximum peak output current
- Rail-to-rail output voltage
- 110 ns maximum propagation delay
- Under Voltage Lock-Out protection (UVLO) with hysteresis
- Wide operating range: 10 to 30 Volts ( $V_{CC}$ )
- Guaranteed performance over temperature  $-40^{\circ}\text{C} \sim +110^{\circ}\text{C}$ .
- Regulatory Approvals
  - UL - UL1577
  - VDE - EN60747-5-5(VDE0884-5)
  - CQC - GB4943.1

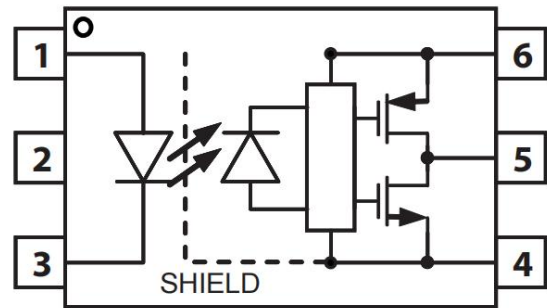
### Applications

- Isolated IGBT/Power MOSFET gate drive
- Industrial Inverter
- AC brushless and DC motor drives
- Induction Heating



### Description

The ICPL-314 series Photocoupler is ideally suited for driving power IGBTs and MOSFETs used in motor control inverter applications and inverters in power supply system. It contains an LED optically coupled to an integrated circuit with a power output stage.

The Photocoupler operational parameters are guaranteed over the temperature range from  $-40^{\circ}\text{C} \sim +110^{\circ}\text{C}$ .



### ORDERING INFORMATION

Outline	Part Number	Package	Marking	Packing	Packing Size	Quantity
	ICPL-314P-500E	LSOP6	314P/W /YYWW	Reel	13 "	3000
	ICPL-314W-500E	LSOP6		Reel	13 "	3000

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**PIN CONFIGURATION AND FUNCTIONS**

	Pin	Name
	1	Anode
	2	NC
	3	Cathode
	4	V <sub>SS</sub>
	5	V <sub>O</sub>
	6	V <sub>CC</sub>

TRUTH TABLE			
LED	V <sub>CC</sub> -V <sub>SS</sub> (Turn-ON, +ve going)	V <sub>CC</sub> -V <sub>SS</sub> (Turn-OFF, -ve going)	VO
Off	0V to 30V	0V to 30V	Low
On	0V to 6.9V	0V to 5.9V	Low
On	6.9V to 8.7V	5.9V to 7.5V	Transition
On	8.7V to 30V	7.5V to 30V	High

Note: A 0.1μF bypass capacitor must be connected between Pin 4 and 6.

### ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Min	Max	Unit	Note
Storage Temperature	$T_{stg}$	-55	125	°C	-
Operating Temperature	$T_{opr}$	-40	110	°C	-
Output IC Junction Temperature	$T_J$	-	125	°C	-
Total Output Supply Voltage	$(V_{CC}-V_{SS})$	0	35	V	-
Average Forward Input Current	$I_F$	-	20	mA	-
Reverse Input Voltage	$V_R$	-	5	V	-
“High” Peak Output Current	$I_{OH(PEAK)}$		1	A	1
“Low” Peak Output Current	$I_{OL(PEAK)}$		1	A	1
Output Voltage	$V_{O(PEAK)}$	-0.5	$V_{CC}$	V	-
Power Dissipation	$P_I$	-	45	mW	-
Output IC Power Dissipation	$P_O$	-	250	mW	-
Lead Solder Temperature	$T_{sol}$	-	260	°C	-

Note: Ambient temperature = 25°C, unless otherwise specified. Stresses exceeding the absolute maximum ratings can cause permanent damage to the device. Exposure to absolute maximum ratings for long periods of time can adversely affect reliability.

Note 1: Exponential waveform. Pulse width  $\leq 10 \mu s$ ,  $f \leq 15 \text{ kHz}$

### RECOMMENDED OPERATION CONDITIONS

Parameter	Symbol	Min.	Max.	Unit
Operating Temperature	$T_a$	-40	110	°C
Supply Voltage	$V_{CC}$	10	30	V
Input Current (ON)	$I_{F(ON)}$	7	16	mA
Input Voltage (OFF)	$V_{F(OFF)}$	-3.0	0.8	V

**ELECTRICAL OPTICAL CHARACTERISTICS**

Parameter	Symbol	Min	Typ	Max	Unit	Test Condition	Note
<b>INPUT CHARACTERISTICS</b>							
Forward Voltage	$V_F$	1.6	1.9	2.4	V	$I_F = 10 \text{ mA}$	-
Input Forward Voltage Temperature Coefficient	$\Delta V_F / \Delta T_j$	-	-1.237	-	mV/°C	$I_F = 10 \text{ mA}$	-
Input Reverse Voltage	$BV_R$	5	-	-	V	$I_R = 10 \mu\text{A}$	-
Input Threshold Current (Low to High)	$I_{FLH}$	-	0.6	2	mA	$V_O > 5\text{V}, I_O = 0\text{A}$	-
Input Threshold Voltage (High to Low)	$V_{FHL}$	0.8	-	-	V	$V_{CC} = 30 \text{ V}, V_O < 5\text{V}$	-
Input Capacitance	$C_{IN}$	-	60	-	pF	$V_F = 0, f = 1\text{MHz}$	-
<b>OUTPUT CHARACTERISTICS</b>							
High Level Supply Current	$I_{CCH}$	-	1.55	3	mA	$I_F = 10 \text{ mA}, V_{CC} = 30 \text{ V}, V_O = \text{Open}, R_g = 30 \Omega, C_g = 3 \text{ nF}$	
Low Level Supply Current	$I_{CCL}$	-	1.92	3	mA	$I_F = 0 \text{ mA}, V_{CC} = 30 \text{ V}, V_O = \text{Open}, R_g = 30 \Omega, C_g = 3 \text{ nF}$	
High Level Output Voltage	$V_{OH}$	29.4	29.69	-	V	$I_F = 10 \text{ mA}, V_{CC} = 30 \text{ V}, I_O = -100 \text{ mA}$	2,3
Low Level Output Voltage	$V_{OL}$	-	0.17	0.4	V	$I_F = 0 \text{ mA}, I_O = 100 \text{ mA}$	
High Level Output Current	$I_{OH}$	0.8	-	-	A	$I_F = 10 \text{ mA}, V_{CC} = 30 \text{ V}, V_O = V_{CC} - 4$	1
Low Level Output Current	$I_{OL}$	0.8	-	-	A	$I_F = 0 \text{ mA}, V_{CC} = 30 \text{ V}, V_O = V_{SS} + 4$	1
Under Voltage Lockout Threshold	$V_{UVLO+}$	6.9	7.8	8.7	V	$V_O > 5 \text{ V}, I_F = 10 \text{ mA}$	
	$V_{UVLO-}$	5.9	6.9	7.5	V	$V_O < 5 \text{ V}, I_F = 10 \text{ mA}$	

All Typical values at  $T_a = 25^\circ\text{C}$  and  $V_{CC} - V_{SS} = 30\text{V}$ , unless otherwise specified; all minimum and maximum specifications are at recommended operating condition.

Note 1: Maximum pulse width = 10 $\mu\text{s}$ .

Note 2: In this test  $V_{OH}$  is measured with a dc load current. When driving capacitive loads,  $V_{OH}$  will approach  $V_{CC}$  as  $I_{OH}$  approaches zero amps.

Note 3: Maximum pulse width = 1ms.

### SWITCHING SPECIFICATION

Parameter	Symbol	Min	Typ	Max	Unit	Test Condition	Note
SWITCHING CHARACTERISTICS							
Propagation Delay Time to Output Low Level	$t_{PHL}$	-	54	110	ns	$R_g = 47\Omega$ , $C_g = 3nF$ , $f = 10kHz$ , Duty Cycle = 50% $I_F = 10mA$ , $V_{CC} = 30V$	-
Propagation Delay Time to Output High Level	$t_{PLH}$	-	69	110	ns		-
Pulse Width Distortion	PWD	-	22	70	ns		-
Propagation Delay Difference Between Any Two Parts	PDD ( $t_{PHL} - t_{PLH}$ )	-100	-	+100	ns		-
Rise Time	$t_r$	-	35	-	ns		-
Fall Time	$t_f$	-	25	-	ns		-
Common Mode Transient Immunity at Logic High	$CM_H$	20	40	-	kV/ $\mu s$	$I_F = 7$ to 16mA, $V_{CC} = 30V$ , $T_a = 25^\circ C$ , $V_{CM} = 1kV$	1,2
Common Mode Transient Immunity at Logic Low	$CM_L$	20	40	-	kV/ $\mu s$	$I_F = 0mA$ , $V_{CC} = 30V$ , $T_a = 25^\circ C$ , $V_{CM} = 1kV$	1,3

All Typical values at  $T_a = 25^\circ C$  and  $V_{CC} - V_{SS} = 30V$ , unless otherwise specified; all minimum and maximum specifications are at recommended operating condition.

Note 1: Pin 2 needs to be connected to LED common.

Note 2: Common mode transient immunity in the high state is the maximum tolerable  $dV_{CM}/dt$  of the common mode pulse,  $V_{CM}$ , to assure that the output will remain in the high state (meaning  $V_O > 10.0V$ ).

Note 3: Common mode transient immunity in a low state is the maximum tolerable  $dV_{CM}/dt$  of the common mode pulse,  $V_{CM}$ , to assure that the output will remain in a low state (meaning  $V_O < 1.0V$ ).

**ISOLATION CHARACTERISTIC**

Parameter	Symbo	Device	Min.	Typ.	Max.	Unit	Test Condition	Note
Withstand Insulation Test Voltage	V <sub>ISO</sub>	ICPL-314P	5000	-	-	V	40% ≤ RH ≤ 60%, t = 1min, T <sub>a</sub> = 25 °C	1,2
		ICPL-314W						
Input-Output Resistance	R <sub>I-O</sub>	-	-	10 <sup>12</sup>	-	Ω	V <sub>I-O</sub> = 500V DC	1

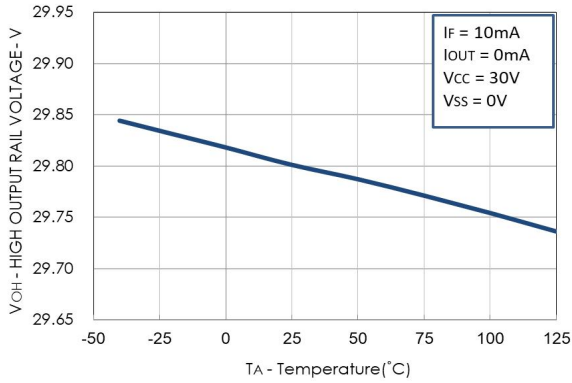
All Typical values at T<sub>a</sub> = 25°C and V<sub>CC</sub> – V<sub>SS</sub> = 30 V, unless otherwise specified; all minimum and maximum specifications are at recommended operating condition.

Note 1: Device is considered a two terminal device: pins 1, 2, 3 are shorted together and pins 4, 5, 6 are shorted together.

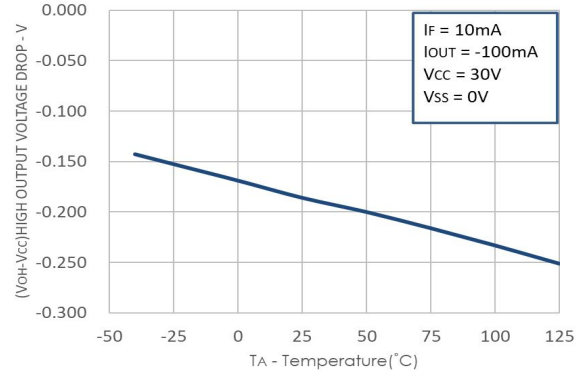
Note 2: According to UL1577, each photocoupler is tested by applying an insulation test voltage 6000VRMS for one second. This test is performed before the 100% production test for partial discharge.

**TYPICAL PERFORMANCE CURVES**

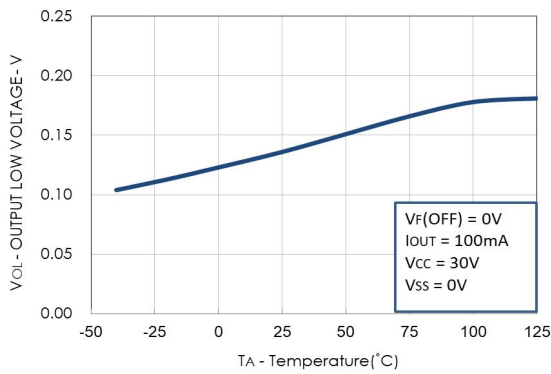
**Fig.1 High output rail voltage vs. Temperature**



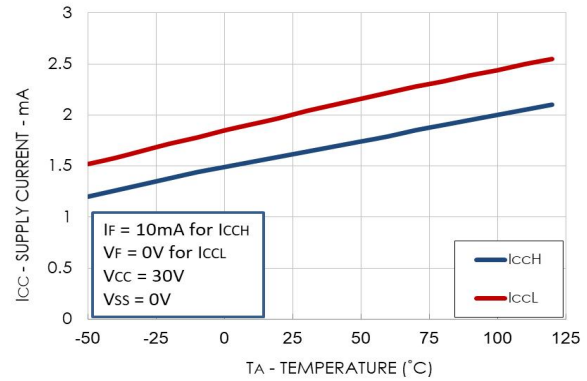
**Fig.2 V<sub>OH</sub> vs. Temperature**



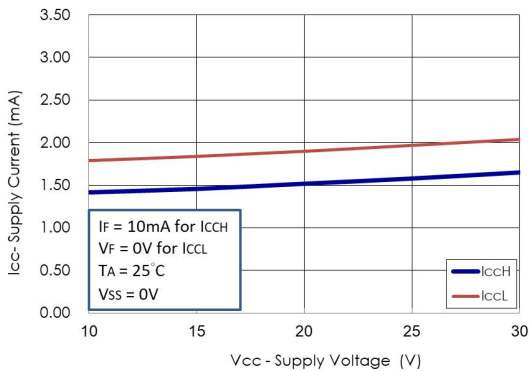
**Fig.3 V<sub>OL</sub> vs. Temperature**



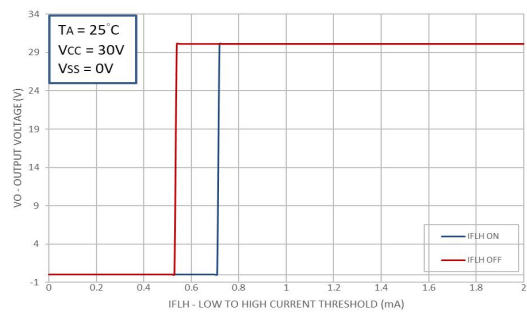
**Fig.4 I<sub>CC</sub> vs. Temperature**



**Fig.5 I<sub>CC</sub> vs. V<sub>CC</sub>**

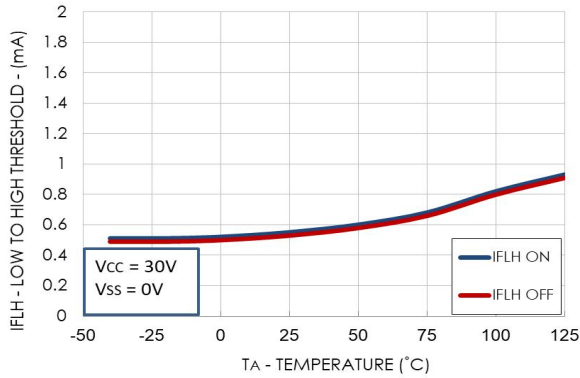


**Fig.6 I<sub>FLH</sub> vs. Hysteresis**

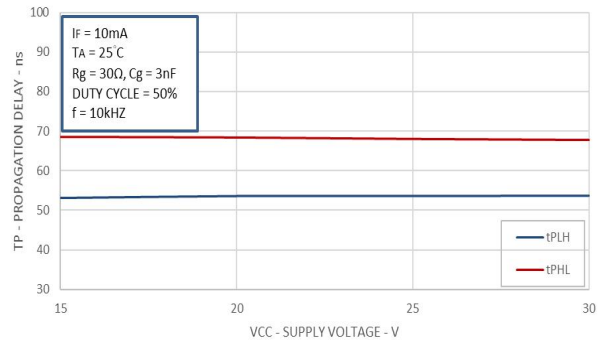




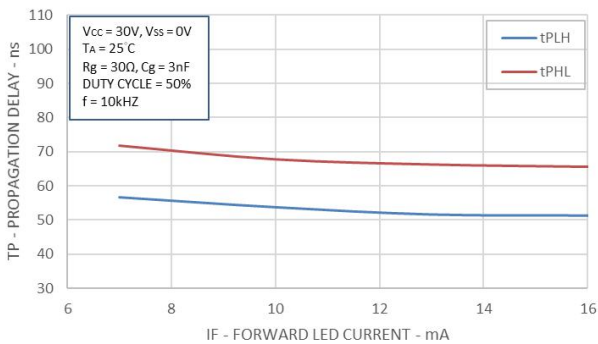
**Fig.7 I<sub>FH</sub> vs. Temperature**



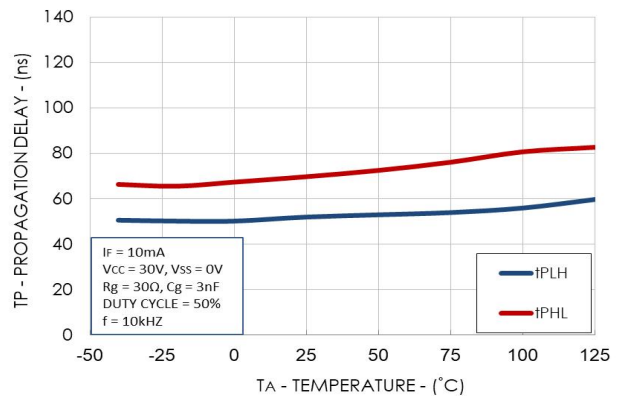
**Fig.8 Propagation Delays vs. V<sub>CC</sub>**



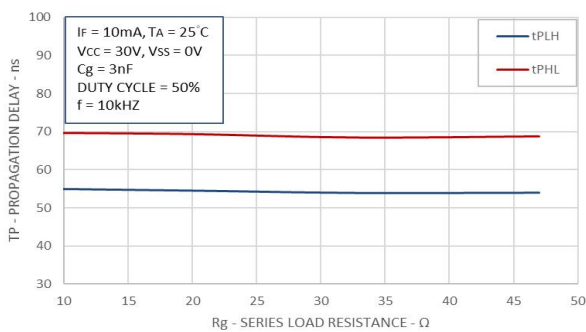
**Fig.9 Propagation Delays vs. I<sub>F</sub>**



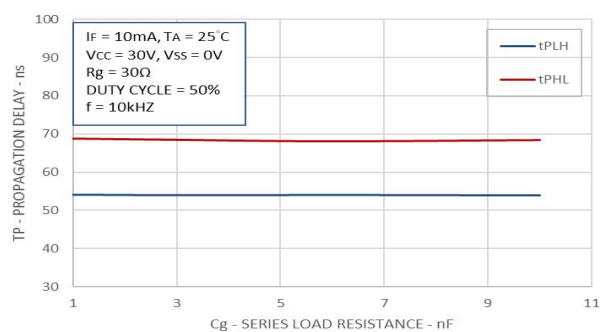
**Fig.10 Propagation Delays vs. Temperature**



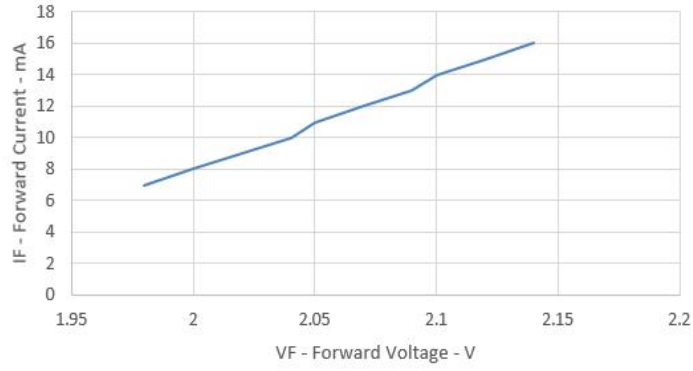
**Fig.11 Propagation Delays vs. R<sub>g</sub>**



**Fig.12 Propagation Delays vs. C<sub>g</sub>**

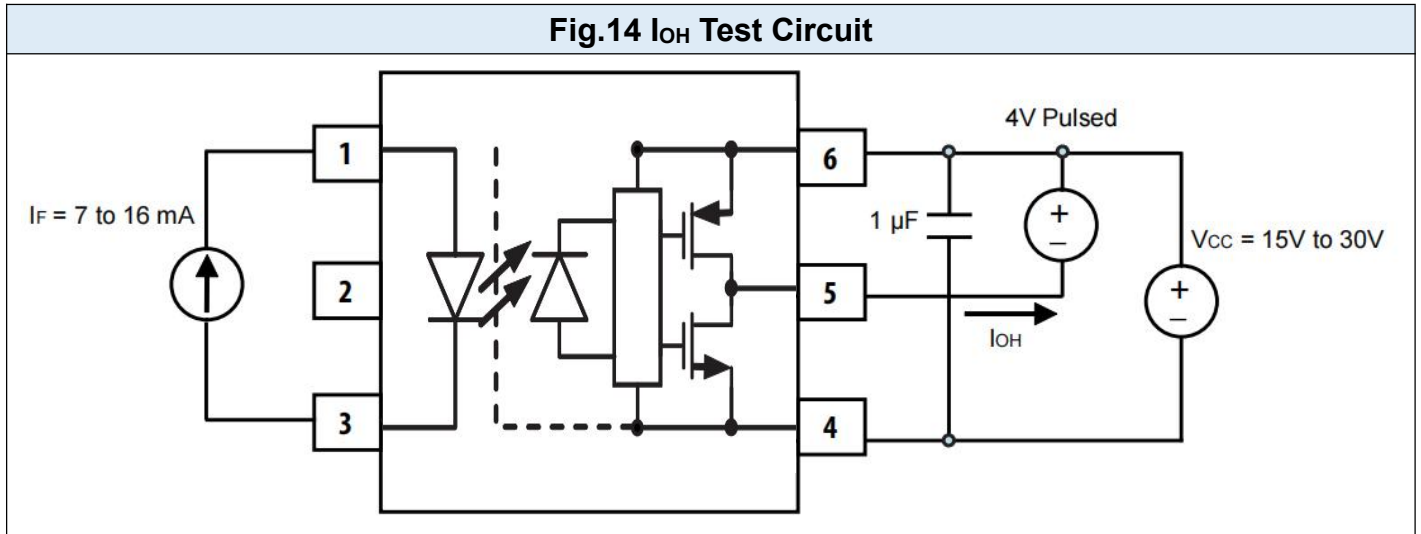


**Fig.13 Input Current vs. Forward Voltage**

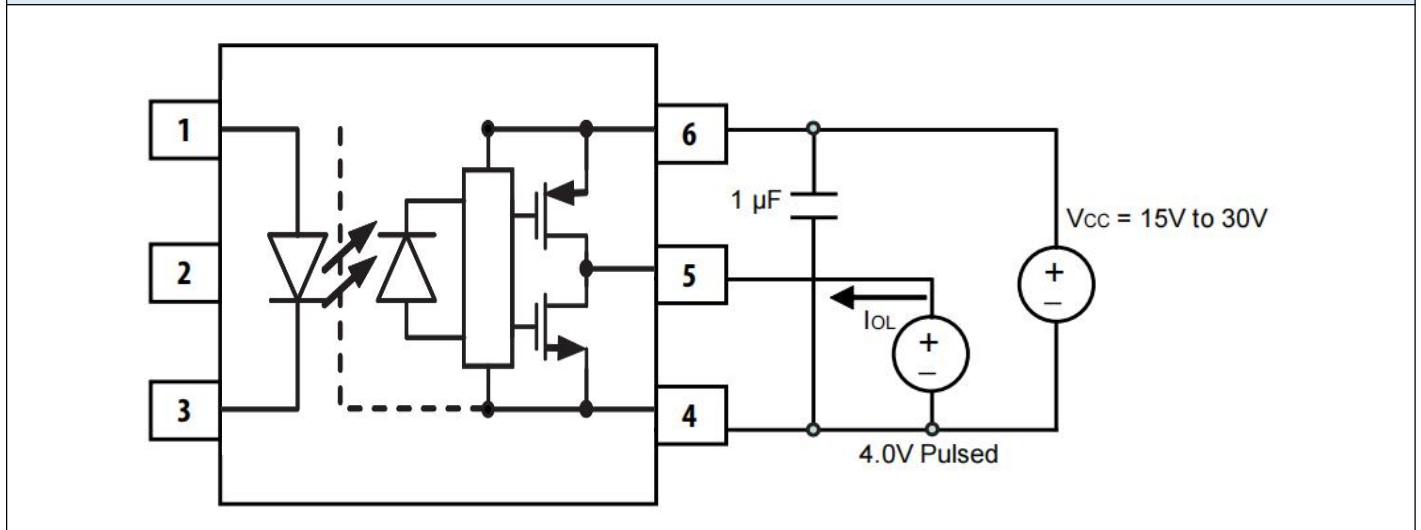


**TEST CIRCUITS**

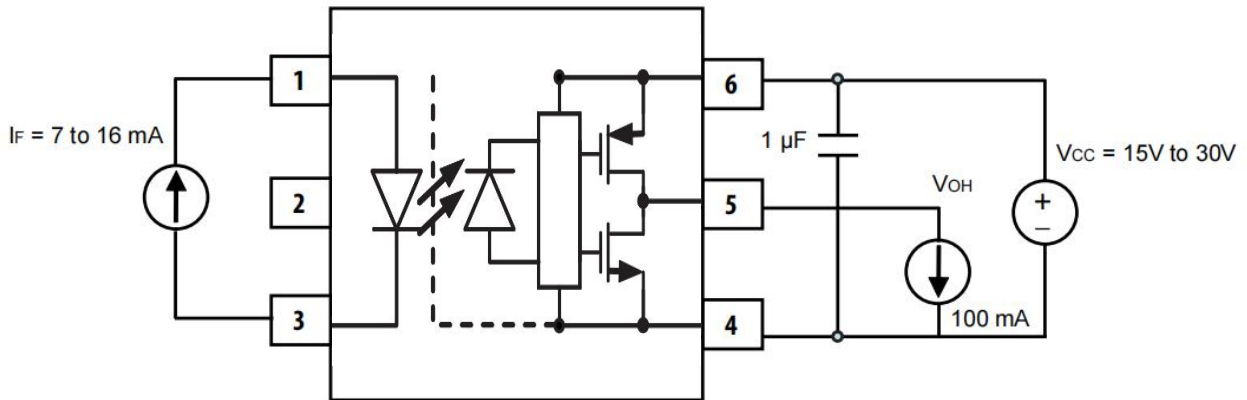
**Fig.14  $I_{OH}$  Test Circuit**



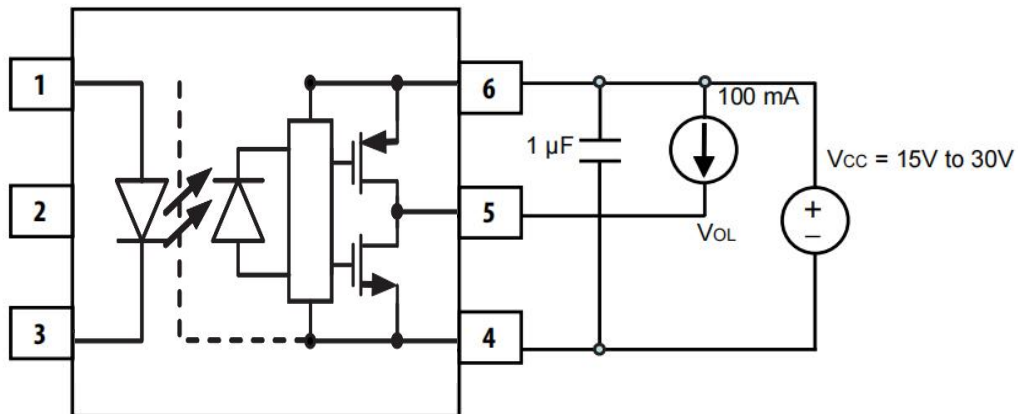
**Fig.15  $I_{OL}$  Test Circuit**



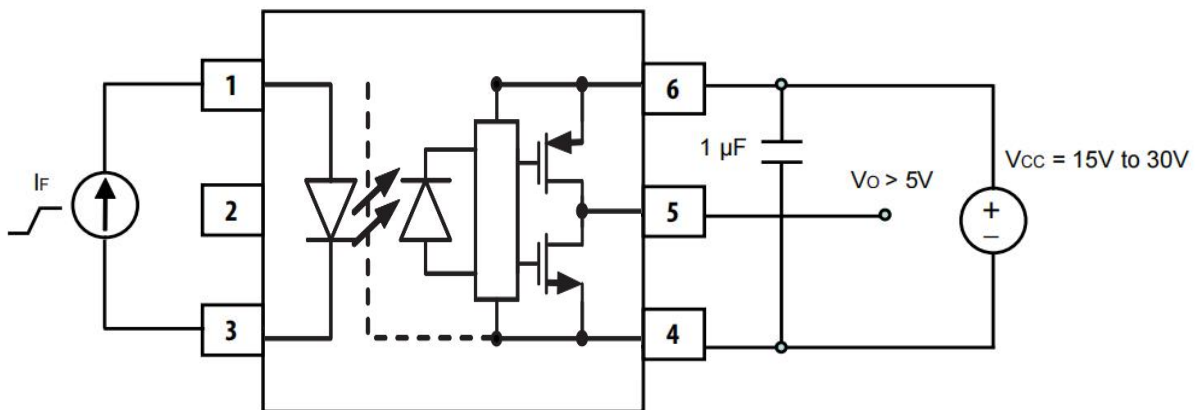
**Fig.16  $V_{OH}$  Test Circuit**



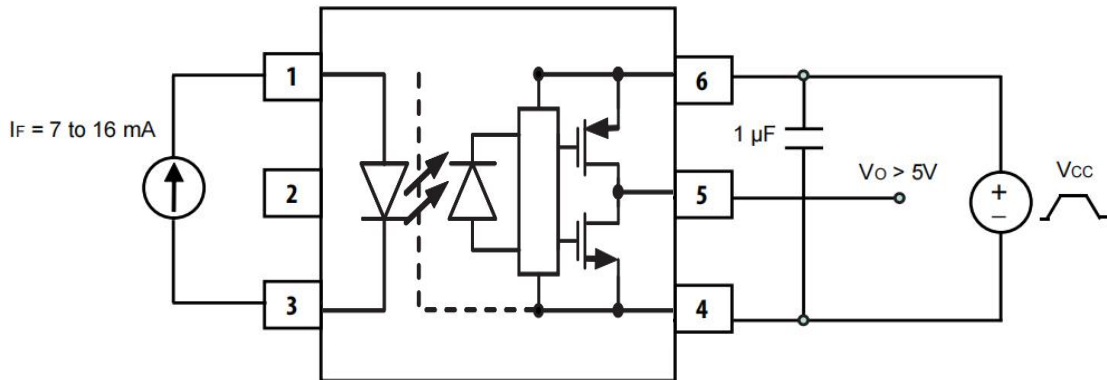
**Fig.17  $V_{OL}$  Test Circuit**



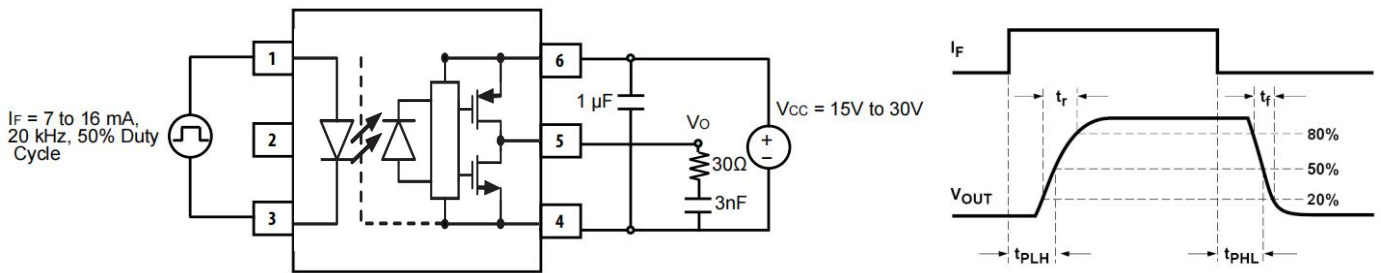
**Fig.18  $I_{FLH}$  Test Circuit**



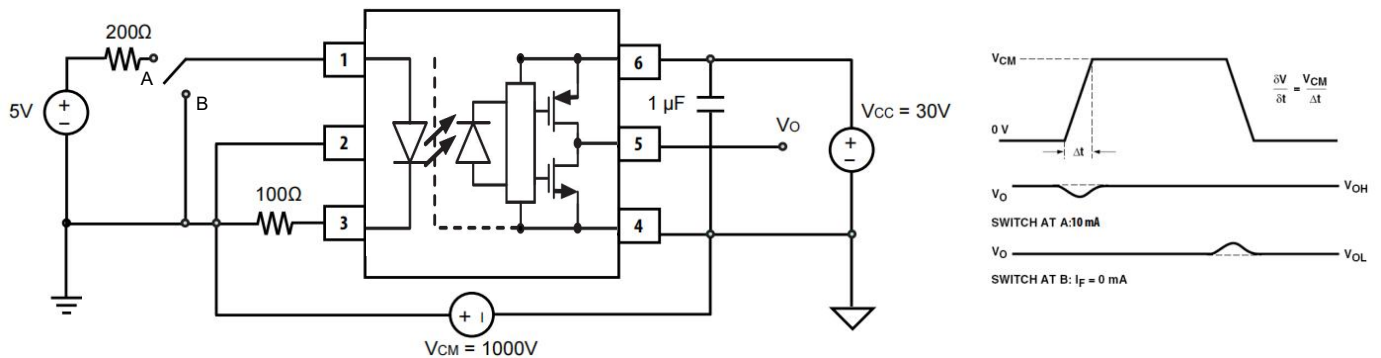
**Fig.19 U<sub>VLO</sub> Test Circuit**



**Fig.20 t<sub>PHL</sub>, t<sub>PLH</sub>, t<sub>r</sub> and t<sub>f</sub> Test Circuit and Waveforms**

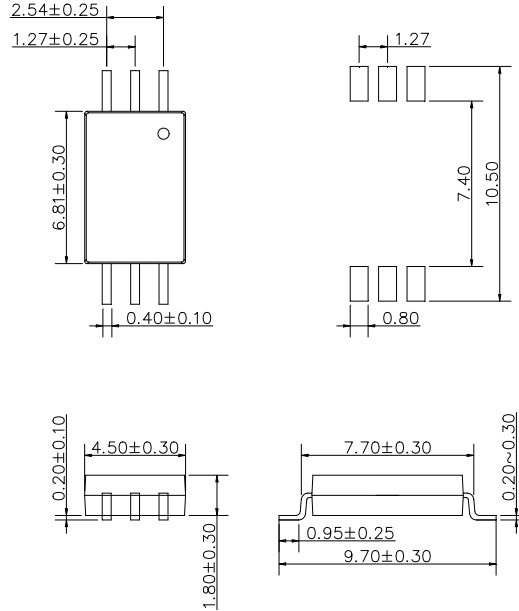


**Fig.21 CMR Test Circuit with Split Resistors Network and Waveforms**

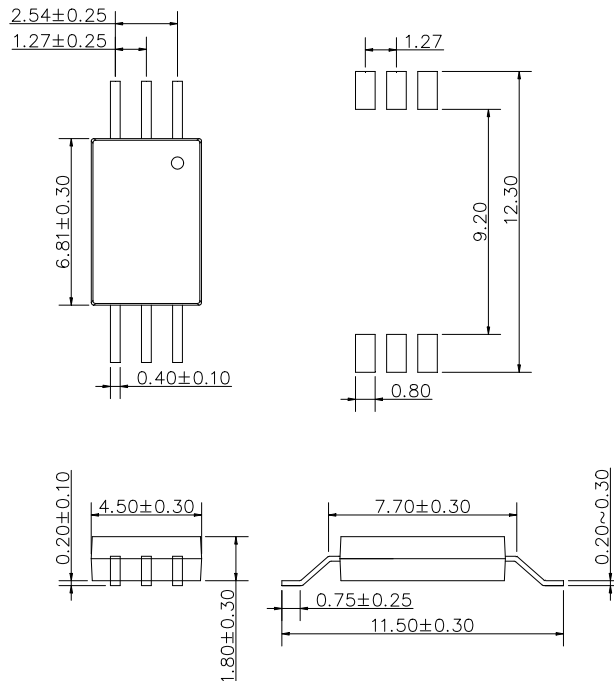


**PACKAGE DIMENSIONS**

**Surface Mount Lead Forming (P type )**



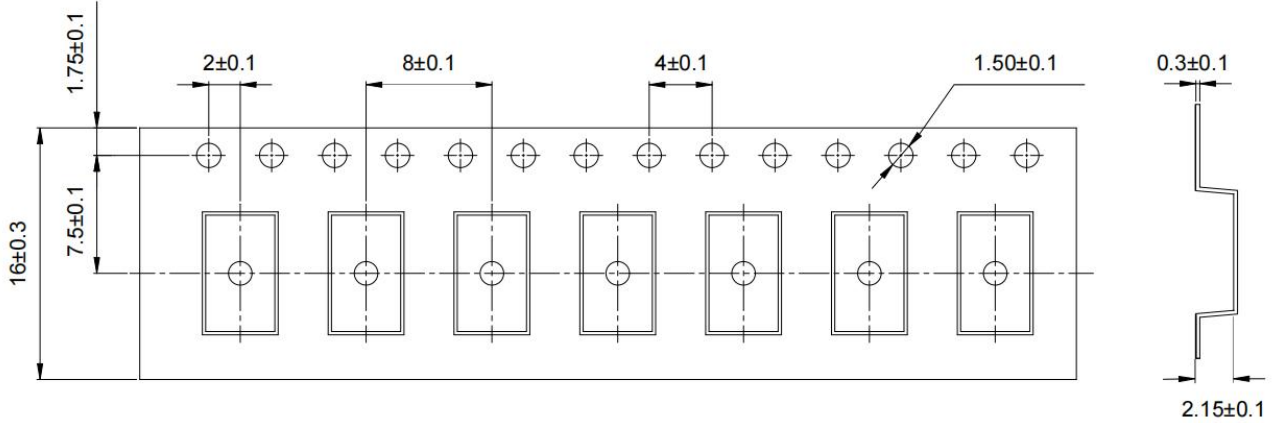
**Surface Mount Lead Forming (W type )**



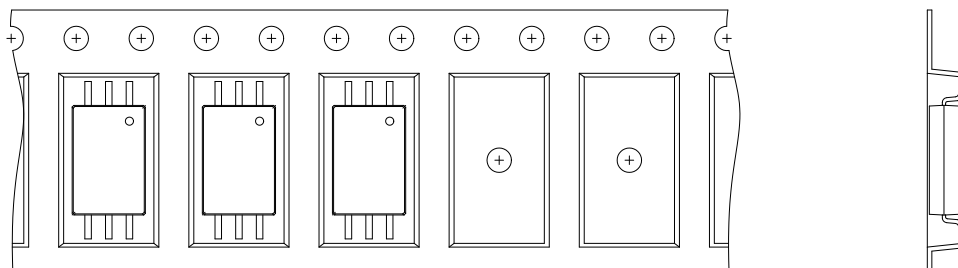
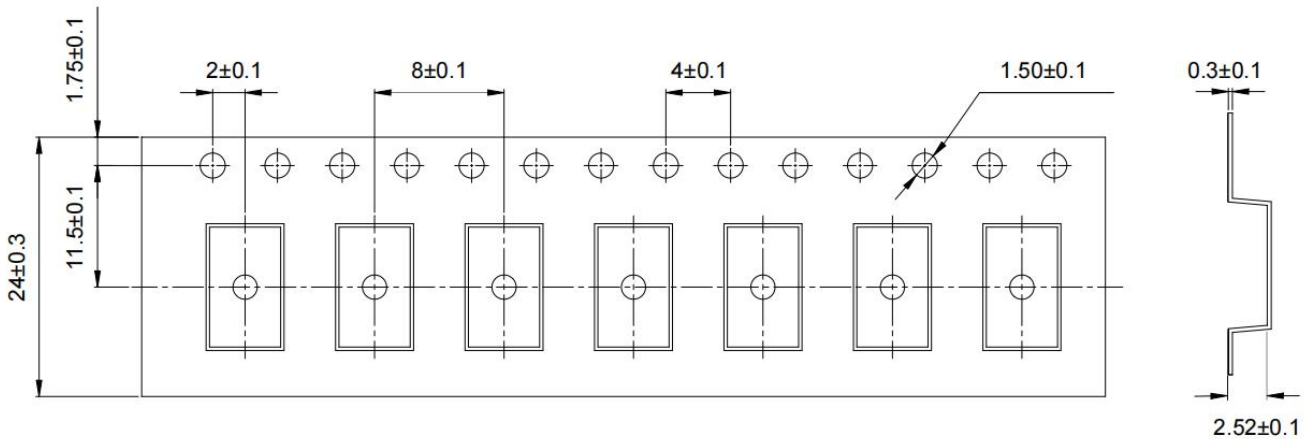
- Dimensions in mm unless otherwise stated

**TAPING DIMENSIONS**

**Option LSOP6-P**



**Option LSOP6-W**

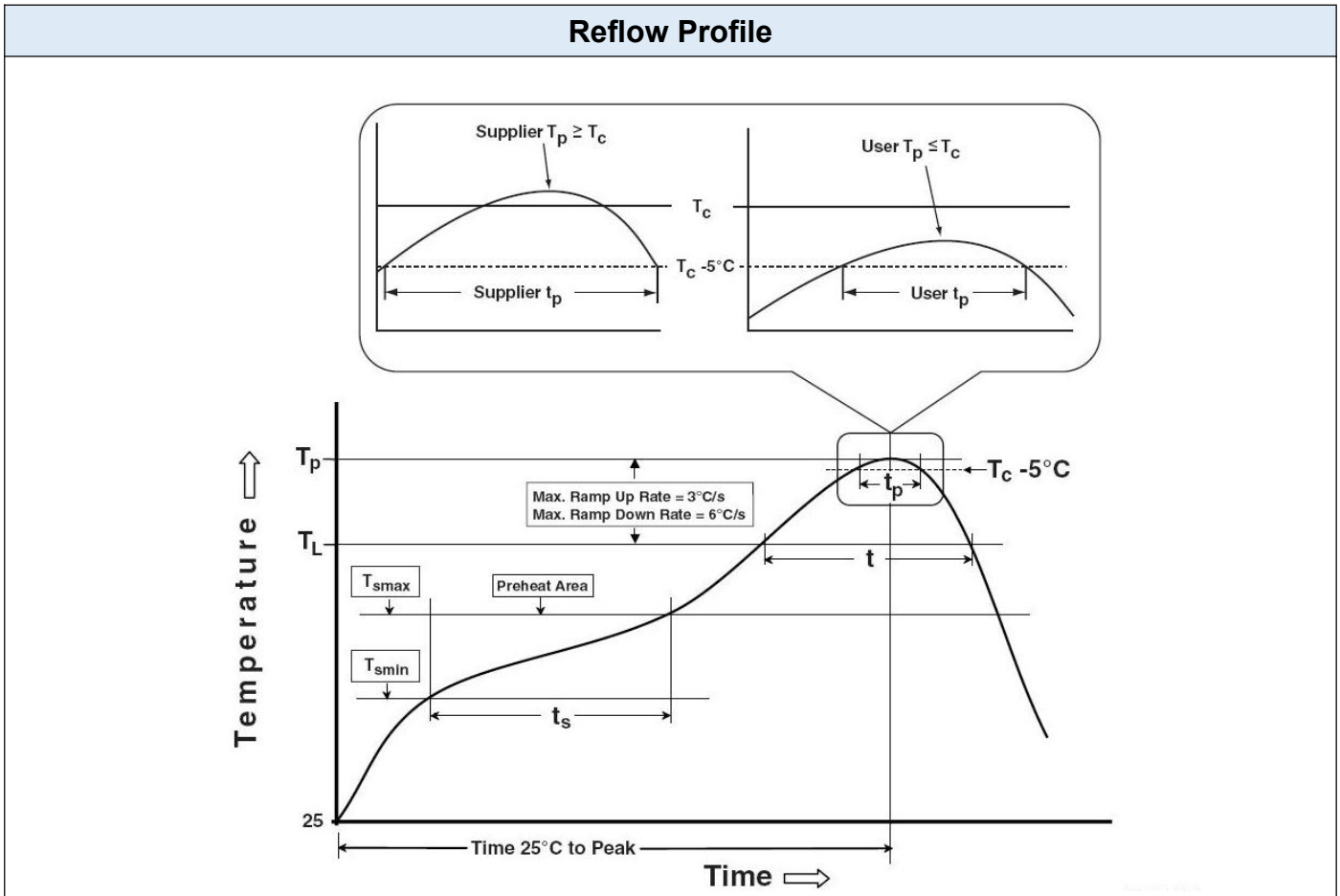


- **Dimensions in mm unless otherwise stated**



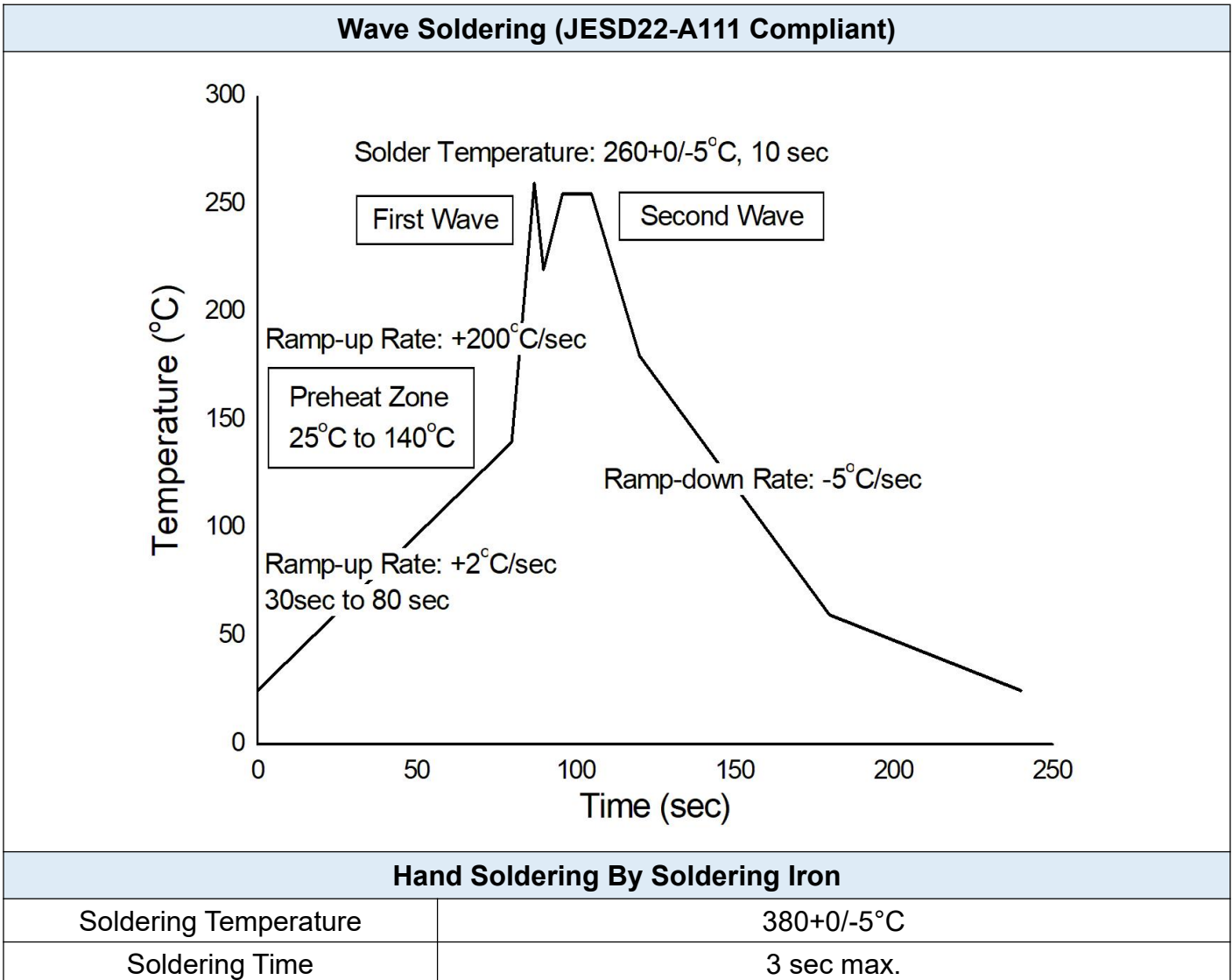


**REFLOW INFORMATION**



Profile Feature	Sn-Pb Assembly Profile	Pb-Free Assembly Profile
Temperature Min. (Tsmin)	100	150°C
Temperature Max. (Tsmax)	150	200°C
Time (ts) from (Tsmin to Tsmax)	60-120 seconds	60-120 seconds
Ramp-up Rate (tL to tP)	3°C/second max.	3°C/second max.
Liquidous Temperature (TL)	183°C	217°C
Time (tL) Maintained Above (TL)	60 – 150 seconds	60 – 150 seconds
Peak Body Package Temperature	235°C +0°C / -5°C	260°C +0°C / -5°C
Time (tP) within 5°C of 260°C	20 seconds	30 seconds
Ramp-down Rate (TP to TL)	6°C/second max	6°C/second max
Time 25°C to Peak Temperature	6 minutes max.	8 minutes max.

**TEMPERATURE PROFILE OF SOLDERING**



- One time soldering is recommended for all soldering method.
- Do not solder more than three times for IR reflow soldering.

## DISCLAIMER

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- Immerge unit's body in solder paste is not recommended.
- Parameters provided in datasheets may vary in different applications and performance may vary over time. All operating parameters, including typical parameters, must be validated in each customer application by the customer's technical experts. Product specifications do not expand or otherwise modify ISOMICRON's terms and conditions of purchase, including but not limited to the warranty expressed therein.
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